

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-15. (Canceled)

16. (Currently Amended) Microcomponent comprising a hermetically-sealed ~~microcavity,~~microcavity having a top side, a left side, and a right side, the microcavity delineated by a cover in which at least one hole is formed, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of ~~polymer or of phosphosilicate glass.~~polymer, the cover encloses the top side, the left side, and the right side of the microcavity, and the cover is one solid layer.

17. (Canceled)

18. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the polymer is selected from photoresists and polyimide.

19-20. (Canceled)

21. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the dimension of the hole is smaller than 5 micrometers.

22. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the hole is arranged on the highest part of the microcavity.

23. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, comprising a plurality of holes.

24. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the thickness of the plug is comprised between 2 and 6 micrometers.

25. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the plug comprises sloping sides.

26. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the plug is non-hermetical.

27. (Currently Amended) Microcomponent according to ~~claim 16~~claim 35, wherein the material of the sealing layer is selected from silicon dioxide, silicon nitride and metals.

28. (Currently Amended) Method for production of a hermetically-sealed microcavity of a microcomponent according to ~~claim 16~~claim 35, successively comprising

- deposition of a sacrificial layer on a substrate,
 - deposition of a first layer forming the cover, on the substrate and sacrificial layer,
 - etching, in the cover, of at least one hole opening out onto the sacrificial layer,
 - removal of the sacrificial layer, via the hole, so as to create the microcavity,
 - deposition of the sealing layer, so as to seal the microcavity hermetically,
- method comprising deposition of the plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited.

29. (Previously Presented) A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;
- deposition of a first layer forming the cover, on the substrate and sacrificial layer;

- etching, in the cover, of at least one hole opening out onto the sacrificial layer;

- removal of the sacrificial layer, via the hole, so as to create the microcavity;

- deposition of the sealing layer, so as to seal the microcavity hermetically;

the method comprising deposition of a plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited;

wherein the plug is made of phosphosilicate glass, and the plug is obtained by a method selected from solgel methods and cathode sputtering.

30. (Previously Presented) Method according to claim 28, wherein the plug is made of a porous material.

31. (Previously Presented) A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;

- deposition of a first layer forming the cover, on the substrate and sacrificial layer;

- etching, in the cover, of at least one hole opening out onto the sacrificial layer;

- removal of the sacrificial layer, via the hole, so as to create the microcavity;

- deposition of the sealing layer, so as to seal the microcavity hermetically;

the method comprising deposition of a plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited;

wherein the plug is made of a porous material; and

wherein, the porous material is a photoresist, and the method comprises a high temperature annealing step.

32. (Previously Presented) Method according to claim 30, wherein the method comprises a pumping step of the gas contained in the microcavity, through the porous material, before the sealing layer is deposited.

33. (Currently Amended) Microcomponent according to claim 16, wherein the microcavity ~~encloses~~ encloses an electromechanical microsystem.

34. (New) Microcomponent comprising a hermetically-sealed microcavity, delineated by a cover in which at least one hole is formed, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of phosphosilicate glass.

35. (New) Microcomponent comprising a sacrificial layer on a substrate, a cover, in which at least one hole is formed, provided over the sacrificial layer and over the substrate at the periphery of the sacrificial layer, a hermetically-sealed microcavity formed by removal of all of the sacrificial layer via the at least one hole, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of polymer.

36. (New) Method according to claim 35, wherein the geometry of the microcavity is defined by the area of the removed sacrificial layer.